















Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 125 FR4 55 L20.35 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_125_FR4_55_L20.35_p10

Layers	in μ	Material	Build-Up	Assembly	
Layer-1	55 μ	Copper		} B	
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-2	35 μ	Copper			
	200 μ	L-FR4			
Layer-3	35 μ	Copper			
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-4	35 μ	Copper			
	200 μ	L-FR4			
Layer-5	35 μ	Copper		} B	
	100 μ	Prepreg			
	100 μ	Prepreg			
Layer-99	55 μ	Copper			

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